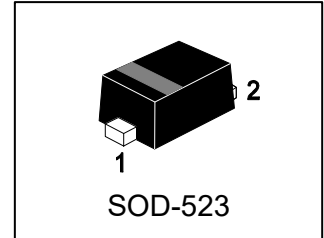


# BAR64-02

## Planar PIN Diode

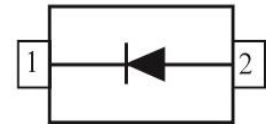
### 1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- Low diode capacitance
- High application frequency
- Very low signal distortion



### 2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
BAR64-02	MD	3000/Tape&Reel



### 3. MAXIMUM RATINGS(In accordance with the Absolute Maximum Rating System IEC134)

Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	VRRM	75	V
Average forward rectified current	IF(AV)	100	mA

### 4. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-5 Board (Note 1) @ TA = 25°C Derate above 25°C	PD	200 1.57	mW mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	RθJA	635	°C/W
Junction and Storage temperature	TJ,Tstg	-55~+150	°C

1. FR-5 = 1.0×0.75×0.062 in.

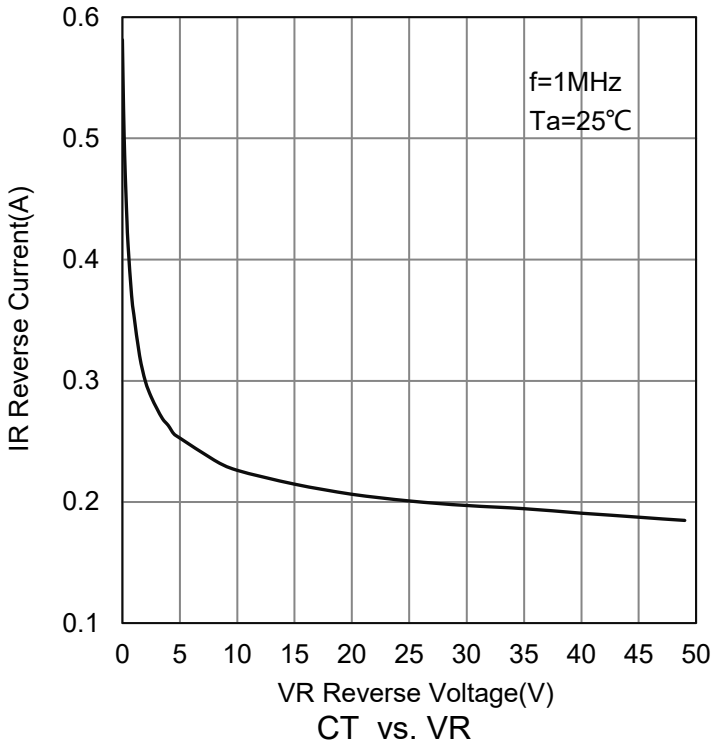
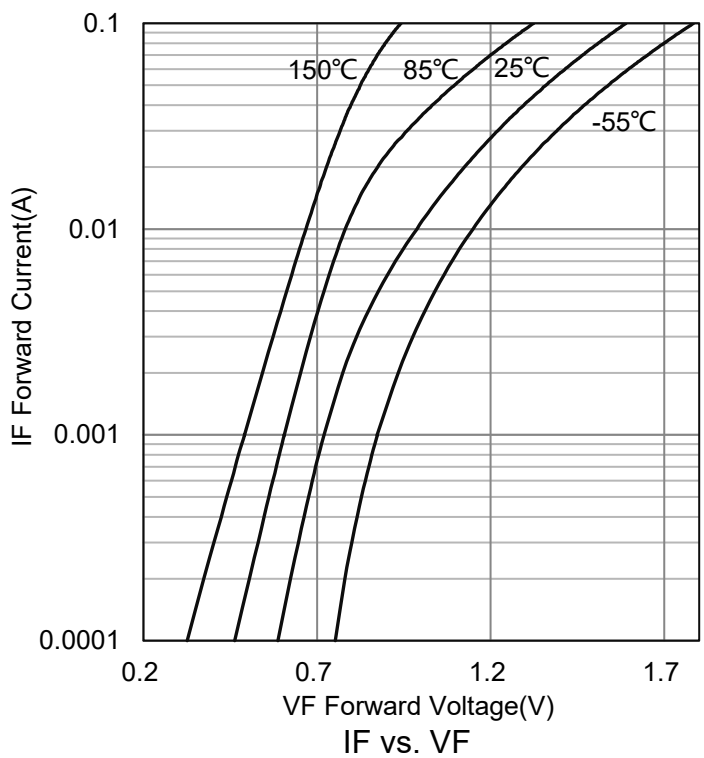
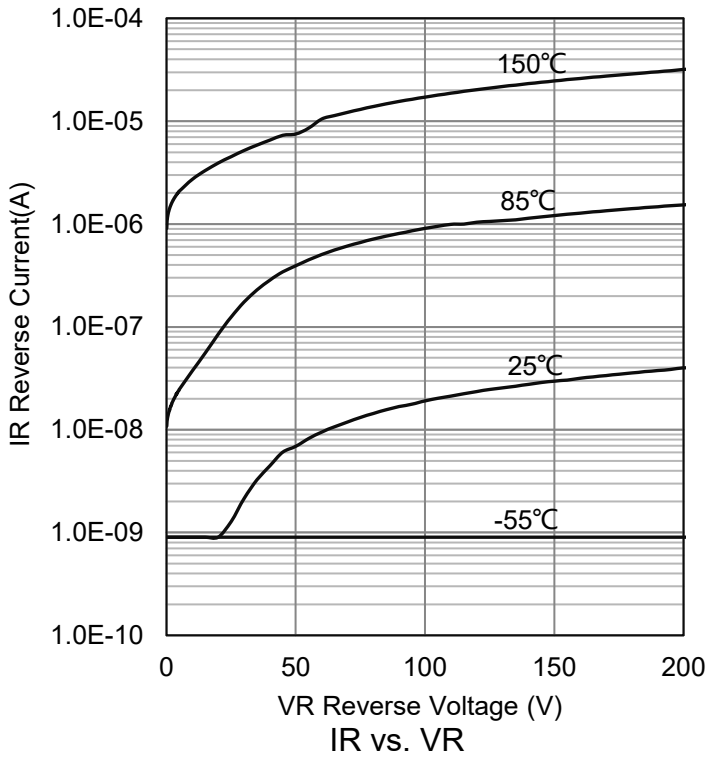


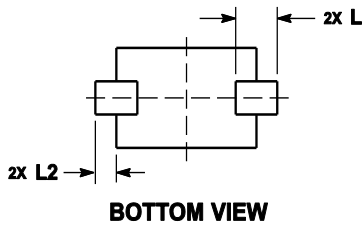
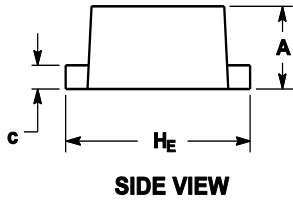
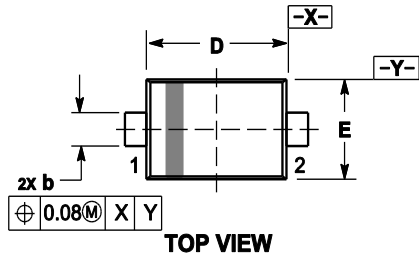
**5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)**

Parameter	Symbol	MIN	MIN	MAX	Unit
Reverse Breakdown voltage (IR=5uA)	VBR	150	-	-	V
Forward Voltage (IF= 50mA)	VF	-	-	1.6	V
Reverse Current (VR = 100 V)	IR	-	-	100	nA
Diode Capacitance (f=1MHz, VR = 0V)	Cd	-	0.48	-	pF
(f=1MHz, VR = 1V)		-	0.34	-	



**6.ELECTRICAL CHARACTERISTICS CURVES**



**7. OUTLINE AND DIMENSIONS**

**Notes:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
E	0.70	0.80	0.90	0.028	0.031	0.035
H <sub>E</sub>	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L <sub>2</sub>	0.15	0.20	0.25	0.006	0.008	0.010

**8. SOLDERING FOOTPRINT**
